



腾戈智慧半导体科技

Top provider of Web-native EDA for
semiconductor yield improvement



TANGO AI

Outline

About Tango AI

Reference

Why Tango AI

Product Capabilities

System Framework

Tango AI At a Glance

Tango - AI, we are the leading information technology service company, provides data analytic solutions to improve yield management, quality enhancement and production control along the entire supply chain manufacturing for semiconductor and electronics companies since year 2000.



How We Help Customers

- Improve their profitability through manufacturing excellence.
- Lower their cost of product design and production control.
- Enhance their yield and quality management.
- Accelerate their production ramp with good traceability and transparency into manufacturing operations.
- Enable their manufacturing insights.

Our Customers: IC Design House

With over 70% of top 20 IC design customers in Taiwan and total 67 Fabless customers worldwide. We provide a full range of service for both frontend and backend customers in the semiconductor industry.

Taiwan

70% market share of
top 20 IC design
customers in Taiwan

Asia

China
Japan
Korea

Global

USA
Germany

Taiwan

Customers rank on the top 20 list in Taiwan

MEDIATEK 联发科(1)
 REALTEK 瑞昱(3)
 HIMAX 奇景(4)
 RICHTEK 立锜(5)
 FOCALTECH 敦泰(7)
 ESMT 晶豪(8)
 SITRONIX 硅创(9)
 SUNPLUS 凌阳(10)
 GLOBALUNICHIP 创意(11)
 RAYDIUM 瑞鼎(13)
 FARADAY 智原(15)
 PIXART 原相(17)
 HOLTEK 盛群(18)
 ALI 扬智(19)

Other Customers in Taiwan

AIROHA 络达	LEADTREND 通嘉
ALCHIP 世芯	LITEON 敦南
ANAXIC 智安	MSTAR 晨星
APMEMORY 爱普	NYQUEST 九齐
BROVOTEK 博发	POWERFLASH 智旺
CHAMPION 虹冠	RALINK 雷凌
ECMOS 飞虹	SIGMASTAR 星宸
EGIS 神盾	SYNCMOS 新茂
FITIPOWER 天钰	SOCLE 虹晶
GENERALPLUS 凌通	SOINC 晶相
HTMobile 恒通	SONIX 松翰
ICATCHTEK 芯鼎	SUNPLUSIT 凌阳创新
ISSI 常忆	UPI 力原
ICPLUS 九暘	UBIQ 力祥
INERGY 广闳	WELTREND 伟詮
ISSC 创杰	ZENTEL 力积
JMICRON 智微	

Asia

China

ALLWINNER 珠海全志
AMLogic 上海晶晨
AUTOCHIPS 合肥杰发
AXERA 爱芯元智
BITMAIN 比特大陆
DJI 深圳大疆创新
HUAYA 上海华亚微
HDSC 上海华大半导体
LEADCORE 上海联芯
MEMSIC 美新半导体
MIRAMEMS 苏州明皜传感
MOORE ELITE 摩尔精英
NOVOSENSE 苏州纳芯微
QSTCORP 上海硅睿
RDA 上海锐迪科
ROCKCHIP 福州瑞芯微
SINOWEALTH 上海中颖微

China

SGMICRO 北京圣邦微
SOLOMON 香港晶门
SPREADTRUM 上海展讯
UNIC 西安紫光国芯
VERISILICON 上海芯原微
XHSC 小华半导体
YTM 苏州云途
TRUECORE 南京真芯润和微
MEGAHUNT 兆讯恒达
PHYTIUM 天津飞腾

Japan

Murata

Global

USA

INVENSENSE 应美盛
MCUBE 硅立
MICRON 美光
ONSEMI 安森美
PIXELWORKS XMEMS 知微电子

Europe

BOSCH 博世

AGSTI 宏发半导体	OSE 华泰电子
ASIT 宏宇半导体	PANTHER 鸿谷科技
CHIPMOS 南茂科技	PTI 力成科技
GIGA-Solution 全智科技	SPIIL 硅品精密
GREATEK 超丰电子	TESTAR 晶测电子
GT 寰邦科技	THAILIN 泰林科技
IST 飞信半导体	THEIL 同欣电子
KYEC 京元电子	UTAC 联测科技

Taiwan

Our Customers : Testing House

SANDISK^(China) 上海晟碟半导体
SANDISK^(Malaysia) 马来西亚
HSTS^(China) 芯测半导体

Global

Why Tango AI ?

Why Tango?

We help you “Bridge All the Big Data High Way”

To accelerate your production ramp, we help to bridge all the production metrics by collecting and aggregating data from multiple manufacturing sites into coherent information and enhance your production efficiency with advanced data science on our “**TANGO**” platform.

We help you “Relieve Your Data Hunting Nightmare”

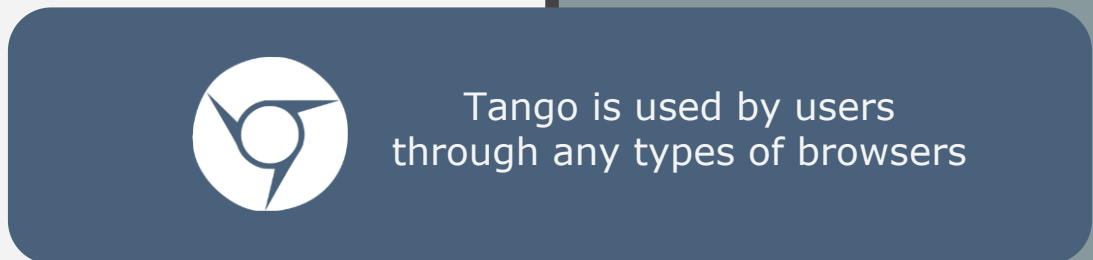
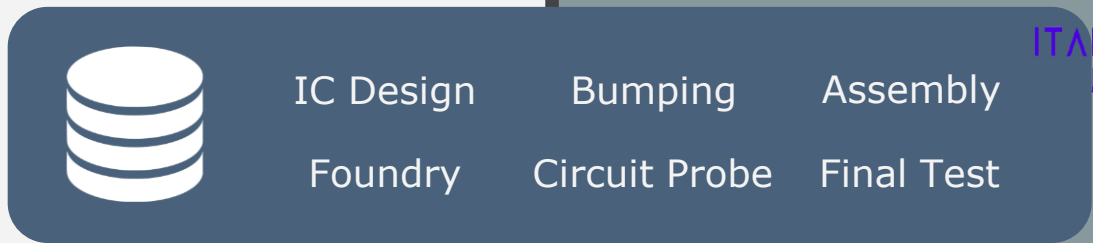
Tango solution helps you to alleviate fishing for a needle in the ocean nightmare and manage your production and yield ramp proactively.

We help you “Detect Your Process Excursion”

We provide an effective monitoring tool to help customers identify process excursion issues at early stage.

Bridge All the Data High Way

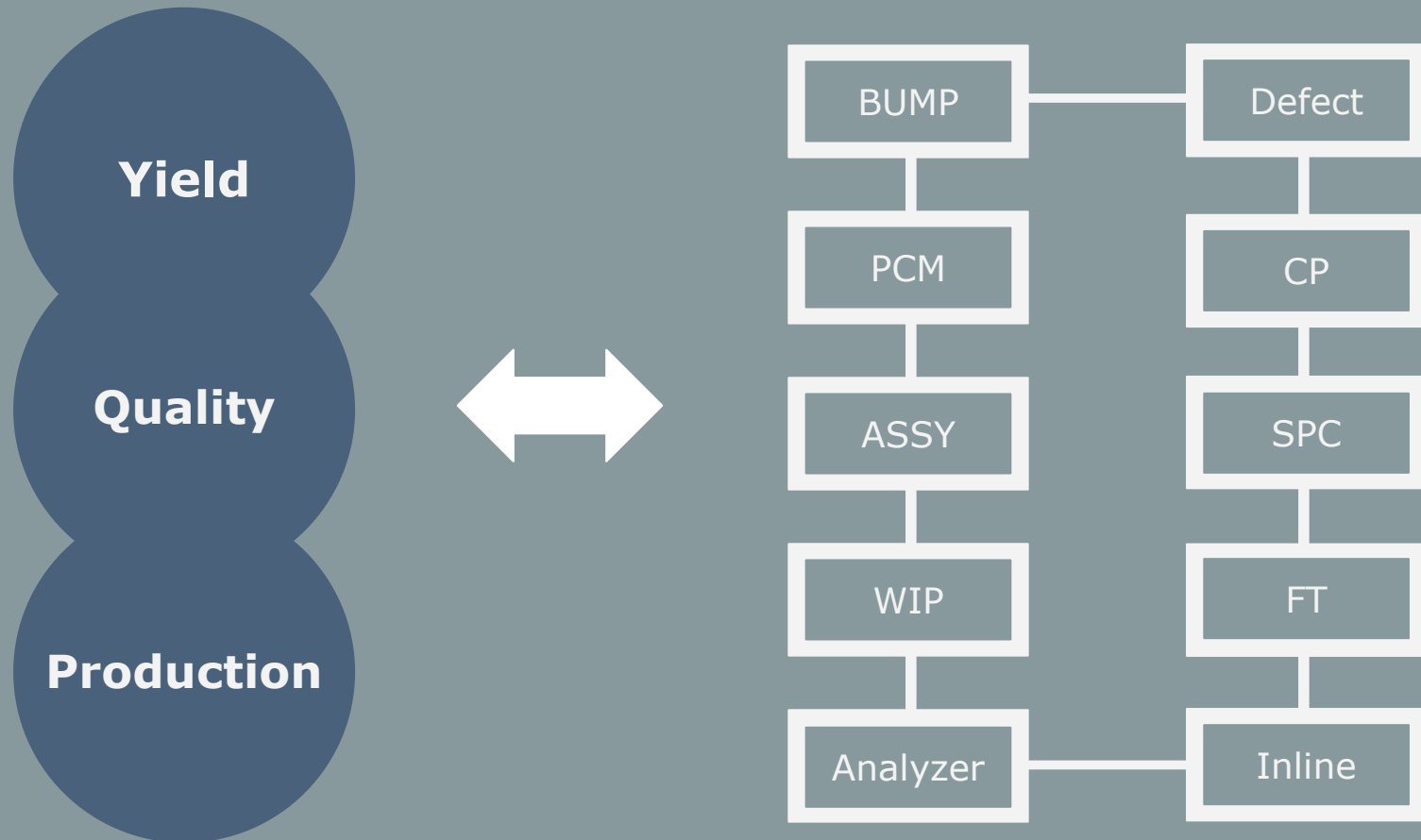
TANGO collect and aggregate data from multiple manufacturing sites and stages, then transform multiple data formats into the coherent format.



Bridge All the Data High Way

Data Integrity:

We extract, secure, clean and standardize the engineering data from multiple manufacturing sites and stages both internally or externally (subcontractors).



Early Excursion Detection

Yield Change Detection

Yield Trend Analysis

Recovery Bin Analysis



Yield Enhancement

Outlier Detection
Escape Prevention Rules
Statistical Process Control
Part Average Testing



Quality Improvement

Full SCM Visibility
Manufacturing Data Monitor
Wafer Map Gallery
Correlation Analysis
Product Sensitivity Analysis



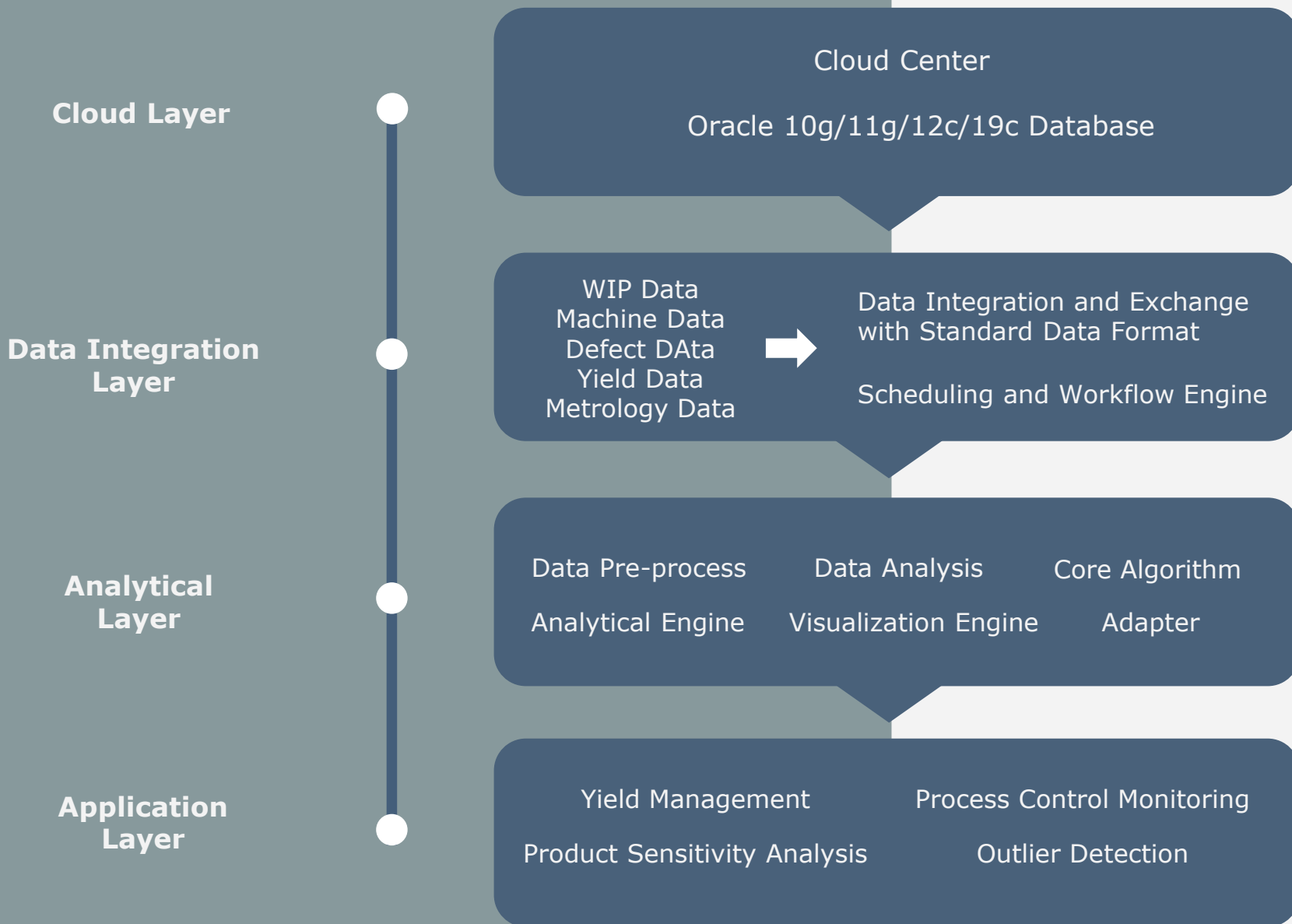
Production Efficiency

TANGO Solutions

We make “Big Data” transform into “Yield Enhancement”, “Quality Improvement” and “Production Efficiency”.

System Framework

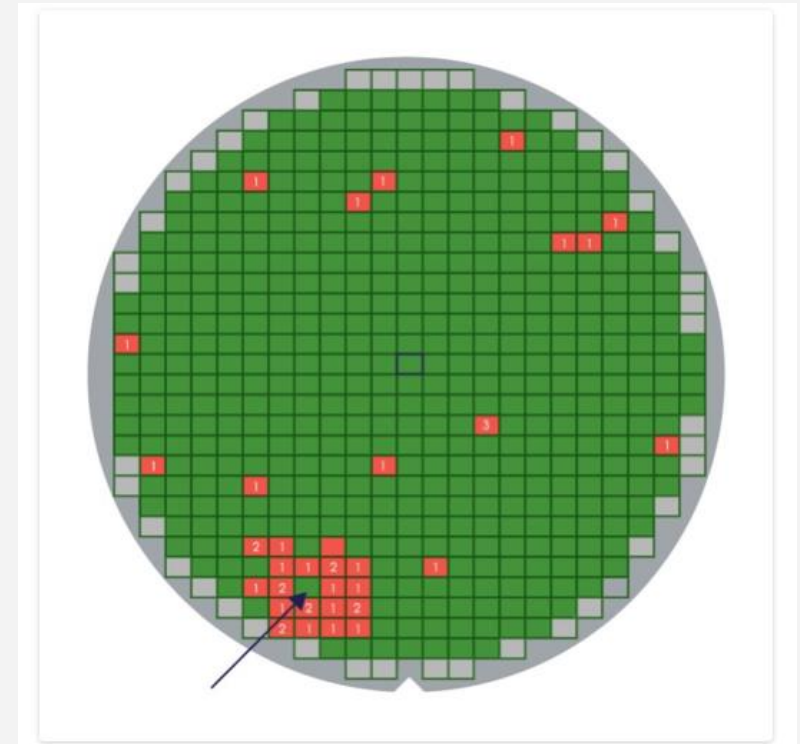
Platform Framework



Product Capabilities

Data Hunting: Detect Suspect Area

We collect wafer maps and reconstruct and consolidate them to recognize failure patterns and remove the highly suspected area.



A good die in a bad neighborhood

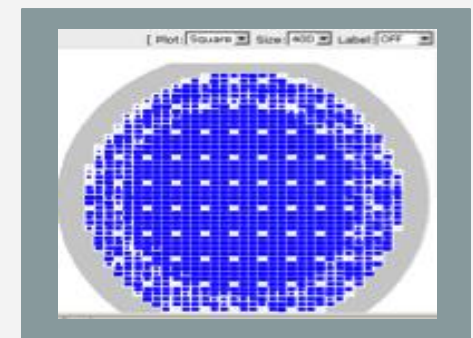
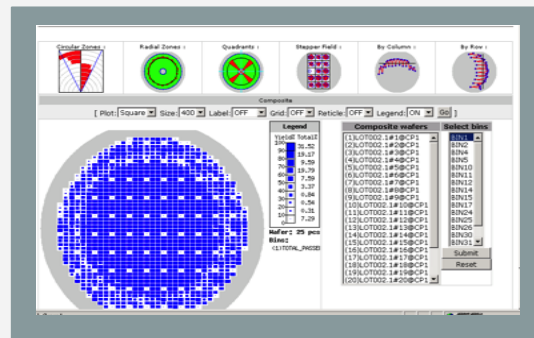
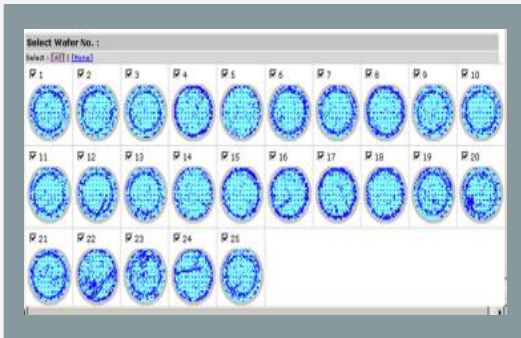
Data Hunting: Detect Suspect Area

As the following steps

Select Wafer Map

Composite Wafer Map

Recognize Pattern





Data Hunting: Proactive Management

Automate outliner warming and data filtering is available to manage thousands of electronic characterized testing measures and parameters to improve operation efficiently and proactively.

Data Hunting:

As the following steps

Data Collecting and Monitoring



IC Design

Bumping

Assembly

Foundry

Circuit Probe

Final Test

Data Analysis



Outliners

Abnormal Parameters

Parts Issue

Failed Pattern

Abnormal Yield

Action and Improvement



Design Improvement

Parts Improvement

Process Improvement



Data Hunting: Supply Chain Traceability

In manufacturing process, systematic and parametric defects are buried throughout the entire supply chain process. Tracking down manufacturing issues is like looking for a needle in a haystack.

Tango solution helps to quickly identify highly correlated test pairs or parametric defects.

Abnormal Yield

Defect

Customer Complain

RMA

IC Design

Foundry

Bumping

Circuit Probing

Assembly

Final Test

Process Issue

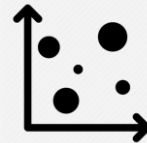
Design Issue

Parts Issue

Equipment Issue



Incident



**Tango
Solution**

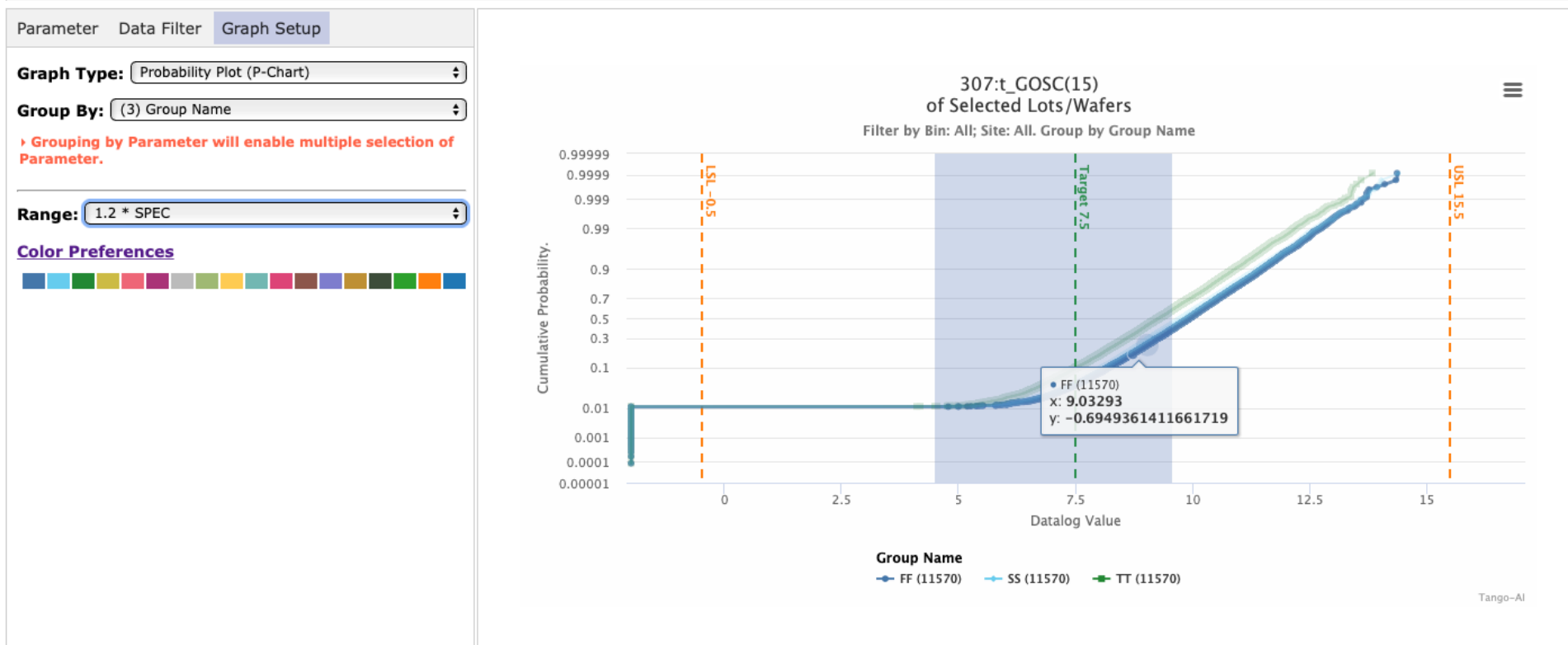


Insight

Data Hunting:
As the following steps

Data Hunting: Supply Chain Traceability

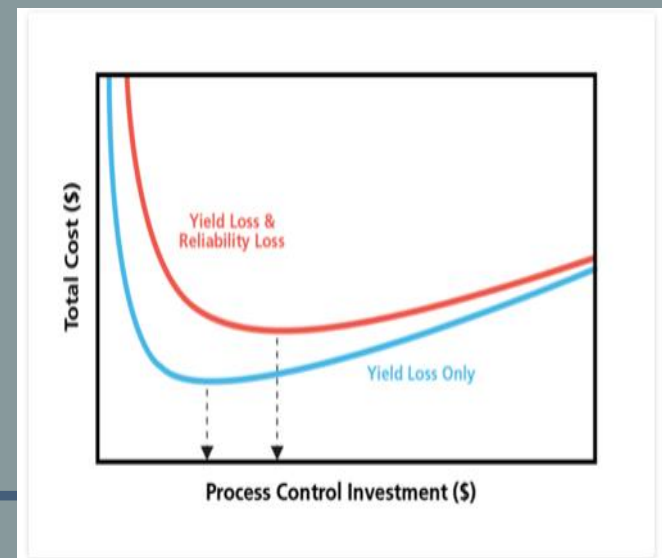
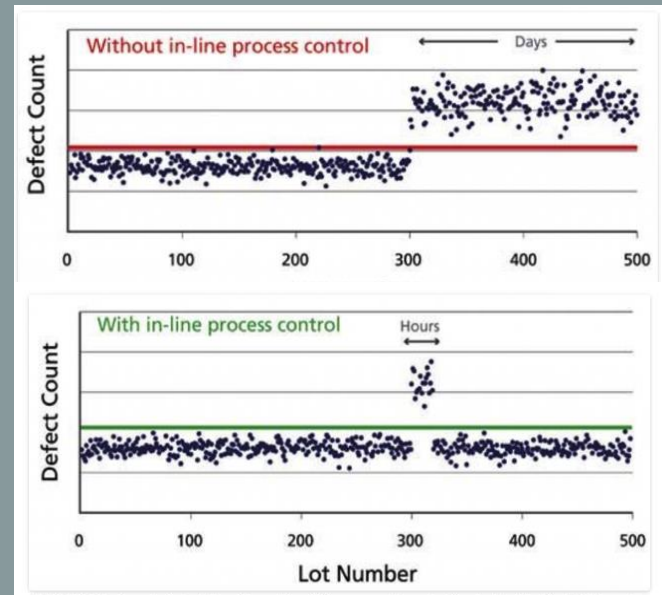
We provide highly interactive data analyzer to accelerate the efficiency of correlation analysis.








Detect Your Process Excursion:

Defect Is Expensive

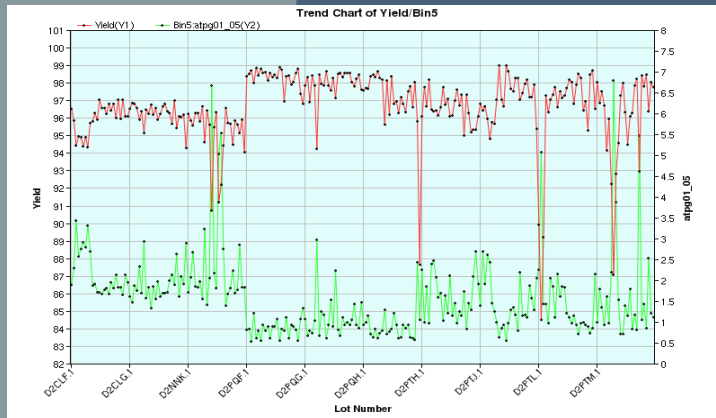
The majority defect cost does not come from large excursions that cause significant yield loss which are usually identified and rectified very early on. Rather, the largest losses usually come from **small excursion that are difficult to detect**.



Detect Your Process Excursion

✓X	Rank #	r ²	Group1	Group2	Chart
<input checked="" type="checkbox"/>	1	0.862032	CONTI_PP_D18	CP1 Bin4	
<input checked="" type="checkbox"/>	2	0.847833	CONTI_NP_D18	CP1 Bin4	
<input checked="" type="checkbox"/>	3	0.719595	BVDS_PAA33_10_D3	CP1 Bin4	
<input checked="" type="checkbox"/>	4	0.584267	IDSAT_PAA33_10_D3	CP1 Bin4	
<input checked="" type="checkbox"/>	5	0.513881	VTI_NAA18_10_D18	CP1 Bin4	
<input type="checkbox"/>	6	0.435769	RSFV_PP_D18_556	CP1 Bin4	
<input type="checkbox"/>	7	0.426996	SPAFI_M6_D46	CP1 Bin4	

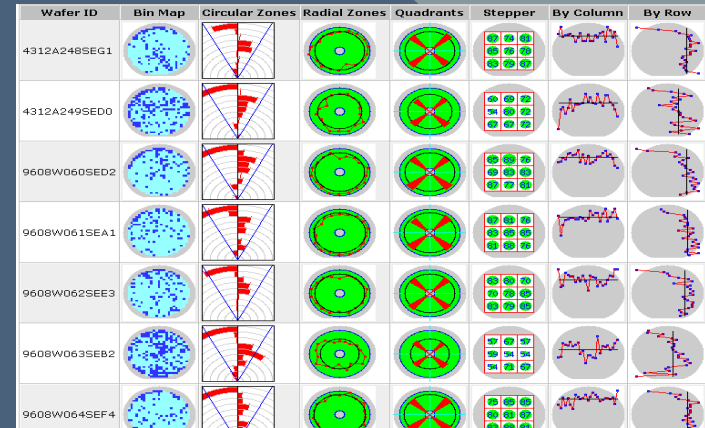
List R-Square Ranking
and Highlight the Top 5



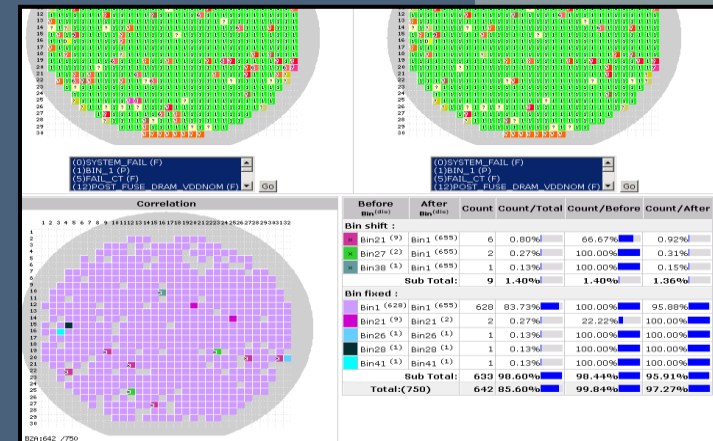
Provide Yield/
Bin Trend Chart

Detect Your Process Excursion

Exhibit Wafer Gallery



Conduct Correlation for wafer re-probing



Test Time Reduction(TTR)

The main idea of TTR is to reduce test items without losing product quality, there are two general methods below:

- 1.By the large number of ICs, remove zero failure rate items*
- 2.By the large number of ICs, remove low PPM failure rate items*

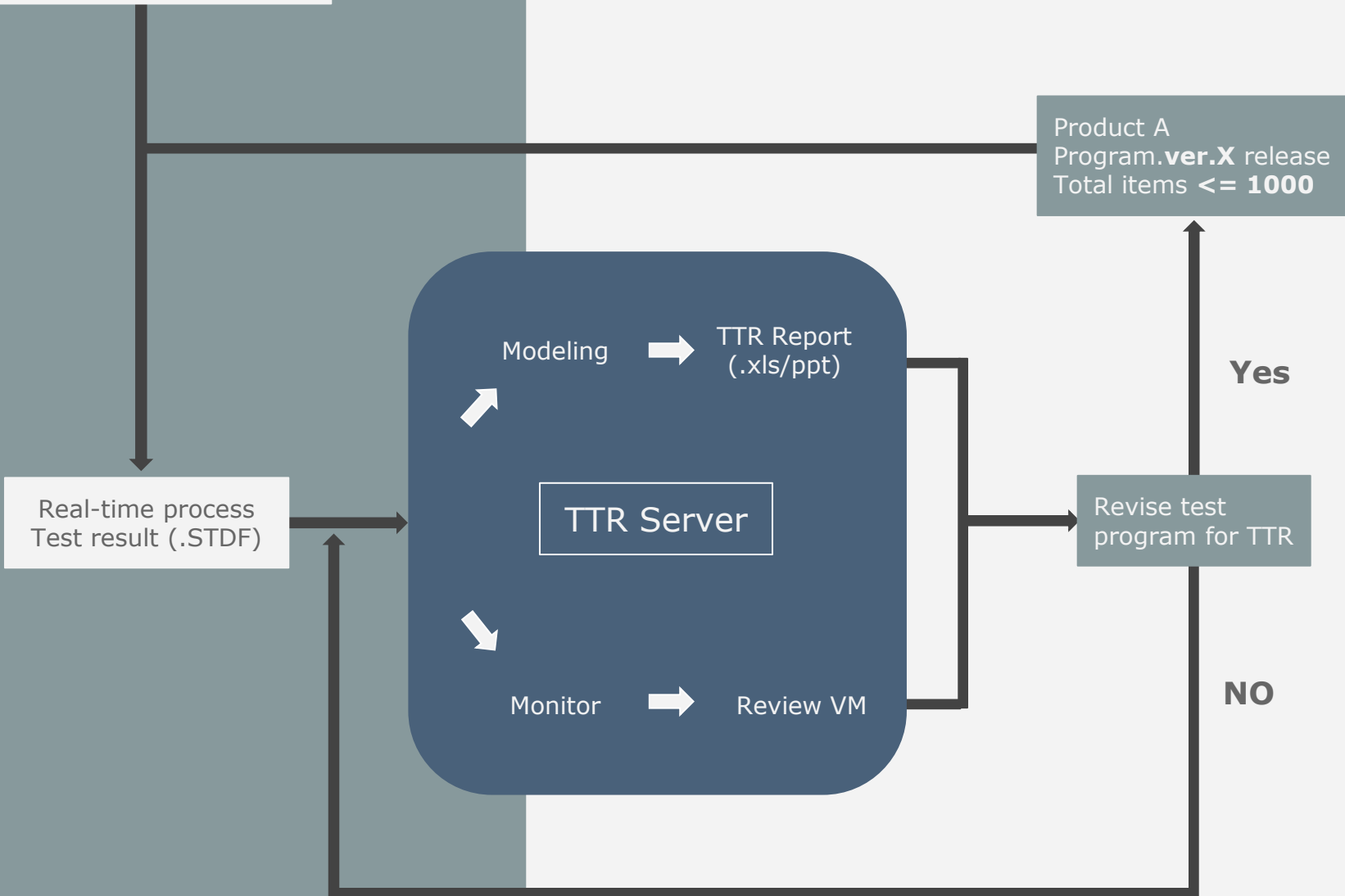
But none of these methods considering the variation of product line, and most important of all, these cant' alarm quality shift.

Strategy: Find the TTR items which can be replaced by other test items immediately, and monitoring them through Virtual Metrology(VM)

- 1.Item Filter:find the TTR items (Correlation/Explanation/Replacement)*
- 2.User confirm TTR Summary、decide TTR List and generate Recipe File*
- 3.Monitor prediction(VM) value of TTR items*

Off-line TTR - Close Loop Operation

Product A
Program. **ver.1** release
Total items = **1000**



AI Techniques for Wafer Map Classification

Take Edge and Line / Scratch Pattern as Example

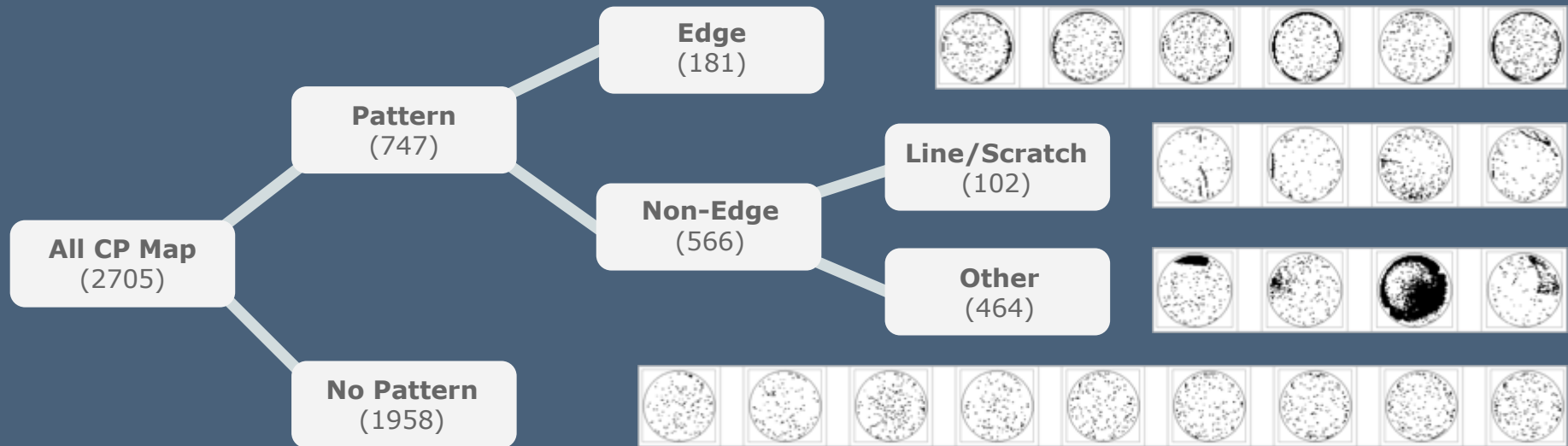
When the bin map exhibits specific patterns, it is usually a clue that equipment problems or process variations have occurred.

Visual inspection by engineers:

- Potential misjudgment due to human fatigue.
- The process can incur significant personnel costs.

Developed Methods Application

Customer A, 2020/03 all wafer



Step 1: Pattern Map Detection

Step 2: Edge Pattern Classification

Step 3: Line Pattern Detection

PAT

GPAT - Spatial Correlation

1.GDBC (Good Die in a Bad Cluster)

- Type A(4) / Type B(8)
- By User Define
- Cut Wafer Edge N Rings

2.Stack / Reticle (by Wafer / Lot)

PPAT - Statistical Outliers

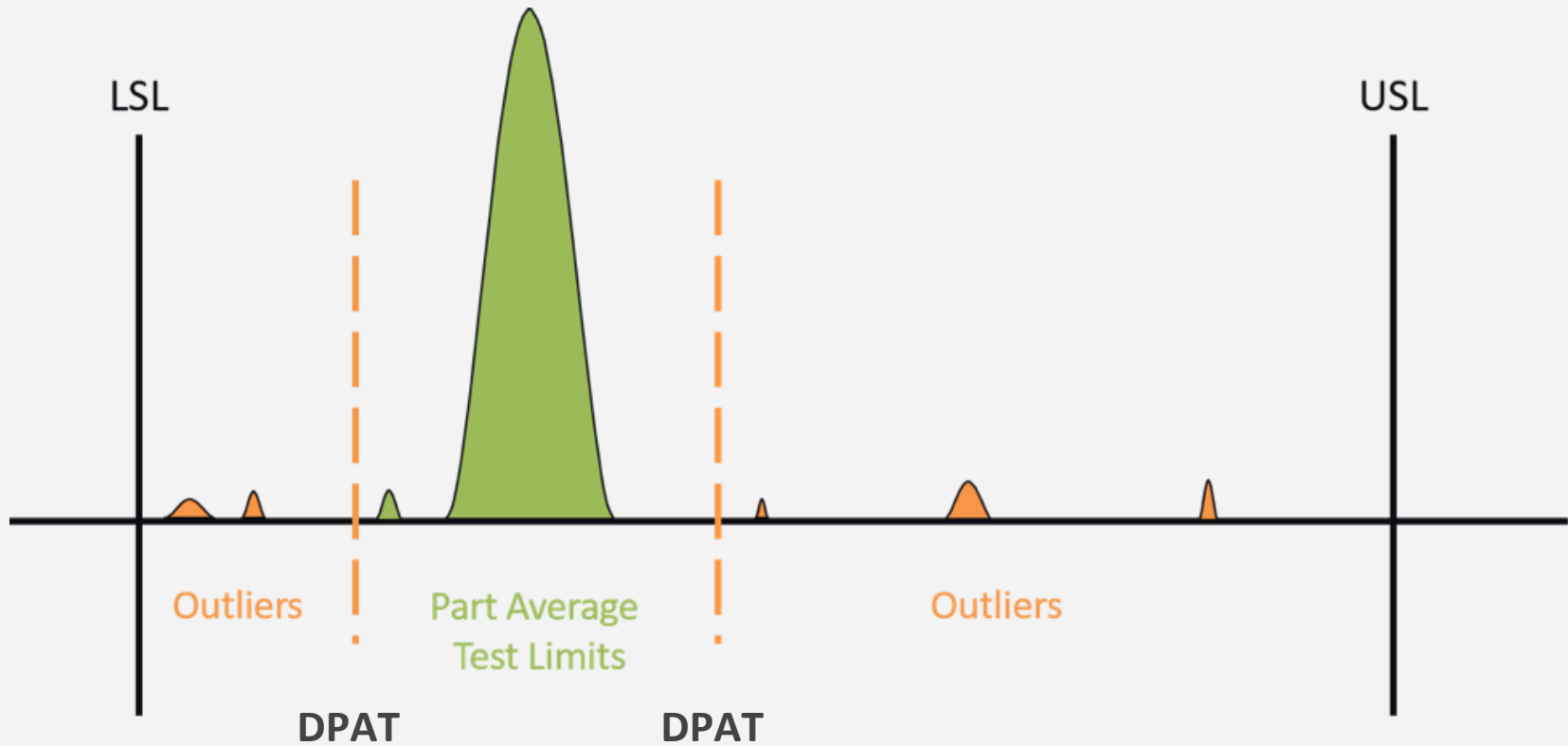
- AEC Standard
- User Define



PPAT

- According to AEC_Q001_Rev D
- Assumption on Gaussian distribution of the test parameters
- Static PAT limit (production, $n > 6$)
 $\text{median} \pm 6 * [(Q3 - Q1) / 1.35]$
- Dynamic PAT limit [passing Static PAT]
 $\text{median} \pm 6 * \text{IQR} / 1.35$

PAT Demonstration



2024 New Functions

ECID Check :

- Pre-define
 1. Test Numbers or Key word of test names (test program)
 2. Checking Rule
- Checking Flow



Yield Simulation

A Flexible Approach to Simulating Yield Based on Stop on Fail Strategy

Order by Test Sequence Displayed in 2 Types of Spec

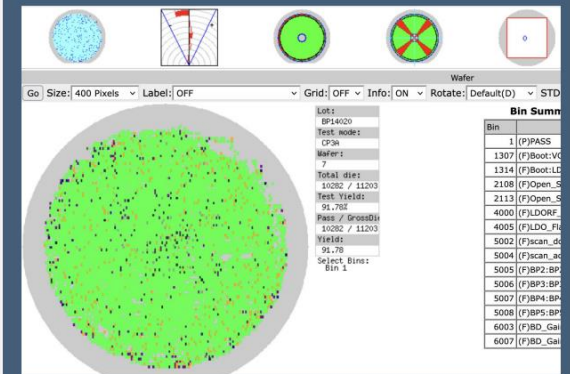
ExecCount_oos	FailCount_oos	FailRate_oos	ExecCount_nSig	FailCount_nSig	FailRate_nSig
243392	0	0.0	243392	69	0.028
243392	0	0.0	243323	125	0.072
243392	0	0.0	243148	16	0.007
243392	0	0.0	243132	49	0.02
243392	0	0.0	243083	23	0.009
243392	0	0.0	243060	26	0.011
243392	0	0.0	243034	23	0.009
243392	0	0.0	243011	25	0.01
243392	0	0.0	242986	75	0.031
243392	0	0.0	242911	16	0.007
243392	0	0.0	242895	25	0.01
243392	0	0.0	242870	24	0.01
243392	0	0.0	242846	5	0.002
243392	0	0.0	242841	9	0.004
243392	0	0.0	242832	0	0.0
243392	0	0.0	242832	618	0.254
243392	39	0.016	242214	244	0.101
243353	11	0.005	241970	111	0.046

Define Spec, Bin and Limits Criteria

LSL	Target	USL	SBin	HBin
0.25	0.725	1.2	2001	2
0.25	0.725	1.2	2013	2
0.25	0.725	1.2	2014	2
0.25	0.725	1.2	2015	2
0.25	0.725	1.2	2016	2
0.25	0.725	1.2	2017	2

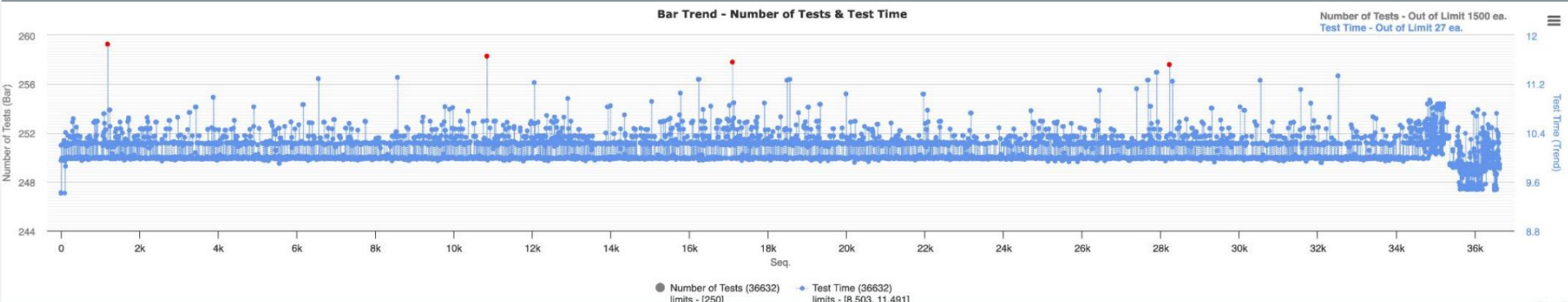
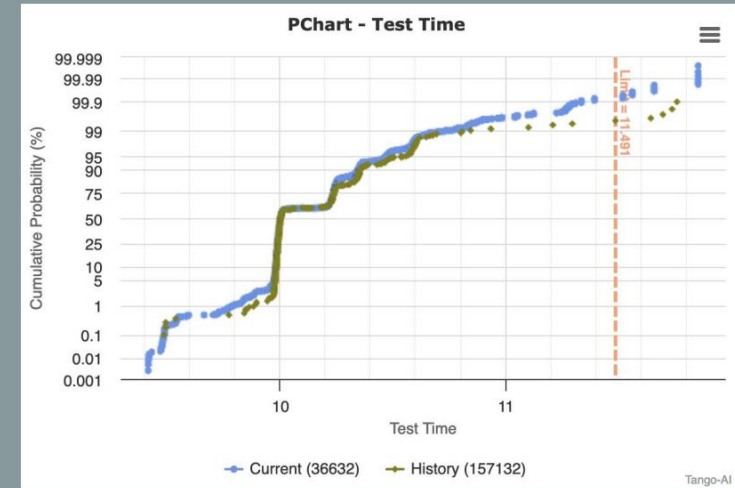
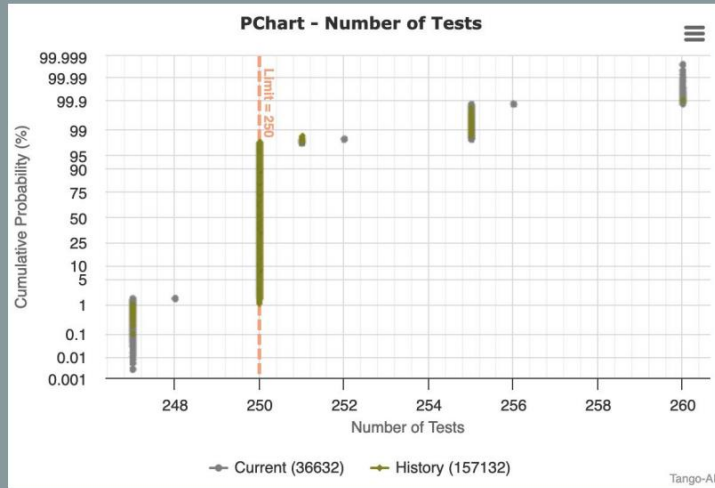
LSL	Target	USL	Center	Variation	nLower	nUpper
0.25	0.725	1.2	<input type="radio"/> Mean <input checked="" type="radio"/> Median	<input type="radio"/> Std <input checked="" type="radio"/> RStd	6	6
0.25	0.725	1.2	<input type="radio"/> Mean <input checked="" type="radio"/> Median	<input type="radio"/> Std <input checked="" type="radio"/> RStd	6	6
0.25	0.725	1.2	<input type="radio"/> Mean <input checked="" type="radio"/> Median	<input type="radio"/> Std <input checked="" type="radio"/> RStd	6	6
0.25	0.725	1.2	<input type="radio"/> Mean <input checked="" type="radio"/> Median	<input type="radio"/> Std <input checked="" type="radio"/> RStd	6	6
0.25	0.725	1.2	<input type="radio"/> Mean <input checked="" type="radio"/> Median	<input type="radio"/> Std <input checked="" type="radio"/> RStd	6	6

Generate New CP Map



FT Anomaly Detection

Efficiently detect outliers from pass die based on number of tests and test time for quality improvement.



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Thank You



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<https://itanggo.com>